

**PATI**



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To the Hon. Commissioner of Patents & Trademarks, Department of Commerce, Washington, DC 20540

all documents or copy

1. Name of conveying party(ies):

Hironobu IKEDA

Additional name(s) of conveying party(ies) attached?  Yes  No

3. Nature of conveyance:

Assignment  Merger

Change of Name  Other

Security Agreement

9.2200

Execution Date: September 14, 2000

2. Name and address of receiving party(ies):

Name:  
NEC CORPORATION

Street Address:  
7-1 Shiba 5-Chome  
Minato-ku, Tokyo  
JAPAN



4. Application number(s) or patent (numbers):

If this document is being filed together with a new application, the execution date of the application is: September 14, 2000

09 667522

A. Patent Application No(s).

B. Patent No(s).

Additional numbers attached?  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:

YOUNG & THOMPSON  
Second Floor  
745 South 23rd Street  
Arlington, VA 22202

6. Total number of applications and patents involved:

One

7. Total fee (37 CFR 3.41).....\$ 40.00

Enclosed  
 Authorized to be charged to deposit account

8. Deposit Account No. 25-0120

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

10/03/2000 BALEXAND 00000041 09667522

02 FC:581 Lauren Terry 40.00 UP  
Name of Person Signing

*Lauren Terry*  
Signature

September 22, 2000  
Date

Total number of pages including cover sheet: **[2]**

ASSIGNMENT

WHEREAS, HIRONOBU IKEDA of Tokyo, Japan

has invented certain new and useful improvements in A CIRCUIT BOARD REDUCING A WARP AND A METHOD OF MOUNTING AN INTEGRATED CIRCUIT CHIP

for which I am about to make application for Letters Patent of the United States of America;

AND WHEREAS, NEC Corporation, 7-1, Shiba 5-chome, Minato-ku, Tokyo, Japan is desirous of acquiring an interest therein and in the Letters Patent to be obtained therefor from the United States;

NOW THEREFORE, be it known by all whom it may concern, that for and in consideration of One Dollars (\$ 1.00) to me in hand paid, the receipt of which is hereby acknowledged the said ASSIGNOR have assigned, sold, and set over, and by these presents do hereby assign, sell, and set over unto the said ASSIGNEE, NEC Corporation the full and exclusive right, title, and interest in and to the said invention, as fully set forth and described in the:

Delete inapplicable wording (a) specification prepared and executed by me on the 14th day of September, 2000, (b) application filed on the day of 19, Serial No.

preparatory to obtaining Letters Patent therefor; said invention, application and Letters Patent to be held and enjoyed by the said ASSIGNEE, NEC Corporation for their own use and behoof, and for their legal representatives, to the full end of the term for which said Letters Patent are granted, as fully and entirely as the same would have been held by me had this assignment and sale not been made.

IN TESTIMONY WHEREOF, I hereunto set my hand and affix my seal at Tokyo, Japan this 14th day of September, A.D. 2000

Hironobu Ikeda (Inventor's full Signature) HIRONOBU IKEDA

Witness: [Signature]

Witness: Hideo Hayashi